

a' rectangular with a greater number of leads on, for example, side a than on smaller size side b.

Paragraph at Page 6, line 7

Q2 FIG. 4a is an enlarged view of a portion of FIG. 4 clearly showing the improved spacing of the bond wires 23a and 23b. When compared with the spacing of bond wires 17a and 17b of FIG. 3 and FIG. 3a, the improvement of the lead frame leads spacing and the bond wire spacing of the lead frame without the tie strap is clearly seen. Bond wires 23a and 23b are from lead frame leads from one side of the lead frame that extend to bond pads on the adjacent side, or from lead frame leads that are in the space where the tie strap has been removed. As illustrated, leads 23a and 23b would be attached to bond pads on side c of semiconductor die 21 if die 21 were square. However, since die 21 is rectangular, leads 23a and 23b extend to side d of die 21. If there were tie bars on the lead frame, this would not be possible since leads 23a and 23b would cross over the tie bar.

Paragraph at Page 6, line 22 (i.e. last paragraph on page 6).

Since there are no tie bars to hold a die mount pad in place, in this embodiment, the semiconductor die is supported by a heat slug 30 which is taped under the lead frame. Heat slug 30 is taped to leads 20 and serves as both a heat sink and a die mount pad.

In the Claims:

Please amend the claims as follows:

- Sub 3/1
- A3
1. A strapless lead frame/heat slug combination, comprising:
a plurality of lead frame leads evenly distributed around a semiconductor die mount; and
a heat slug providing the die mount area, wherein said heat slug is attached under the lead frame with tape.